General Description

The SJS3400B uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a wide variety of applications.

Features

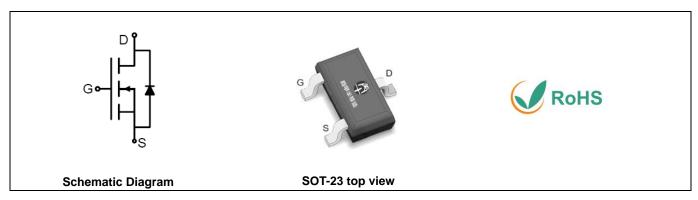
- Low Gate Charge
- High Power and current handing capability
- Lead free product is acquired

Application

- PWM Applications
- Load Switch
- Power Management

Key Performance Parametes

Parameter	Value	Unit
V _{DS}	30	V
R _{DS(ON)_TYP}	19.7	mΩ
I _D	5.8	A
Q _G	20	nC



Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJS3400B	3400B	SOT-23	Tape	\	/	3000 Pcs

Table 1. Absolute Maximum Ratings ($T_A=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V _{DS}	Drain-Source Voltage (V _{GS} =0V)	30	V
V _G s	Gate-Source Voltage (V _{DS} =0V)	±20	V
1-	Drain Current-Continuous(T _A =25°C)	5.8	А
l _D	Drain Current-Continuous(T _A =100°C)	3.7	А
I _{DM} (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	23.2	А
D.	Maximum Power Dissipation(T _A =25°ℂ)	1.4	W
P _D	Maximum Power Dissipation(T _A =100°C)	0.56	W
Eas	Avalanche energy (Note 2)	20	mJ
TJ, TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Тур	Max	Unit
R _{θJA} Thermal Resistance, Junction-to-Ambient			90	°C/W



Table 3. Electrical Characteristics ($T_J=25^{\circ}C$ unless otherwise noted)

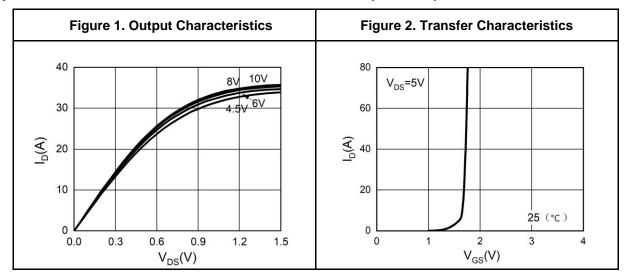
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
On/Off States	•					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	30			V
	7 0 1 1/1 1 2 1 0 1	V _{DS} =30V, V _{GS} =0V T _J =25°C			1	μΑ
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V T _J =125°C			100	μΑ
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±12V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250µA	0.45		1.25	V
g FS	Forward Transconductance	V _{DS} =5V, I _D =2A		7.8		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =3A T _J =25°C		19.7	25.6	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =2A T _J =25°C		21.4	28.5	mΩ
Dynamic Chara	octeristics			•		
Ciss	Input Capacitance			696		pF
Coss	Output Capacitance	V _{DS} =15V,V _{GS} =0V, f=1.0MHz		53		pF
Crss	Reverse Transfer Capacitance			42		pF
Rg	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		1.9		Ω
Switching Para	meters		I.	J		
t _{d(on)}	Turn-on Delay Time			5		nS
t _r	Turn-on Rise Time	V _{GS} =4.5V, V _{DS} =15V,		12		nS
$t_{d(off)}$	Turn-Off Delay Time	R_L =7.5Ω, R_{GEN} =3Ω		24		nS
t_f	Turn-Off Fall Time			2		nS
Q_g	Total Gate Charge			20		nC
Q_{gs}	Gate-Source Charge	V _{GS} =4.5V, V _{DS} =15V, I _D =2A		2		nC
Q_{gd}	Gate-Drain Charge			2.2		nC
Source-Drain D	liode Characteristics			•		
I _{SD}	Source-Drain Current (Body Diode)				5.8	Α
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =2A			1.2	V
t _{rr}	Reverse Recovery Time	I _F =2A, dI/dt=100A/μs		8.5		ns
Qrr	Reverse Recovery Charge	I _F =2A, dI/dt=100A/μs		3.4		nC

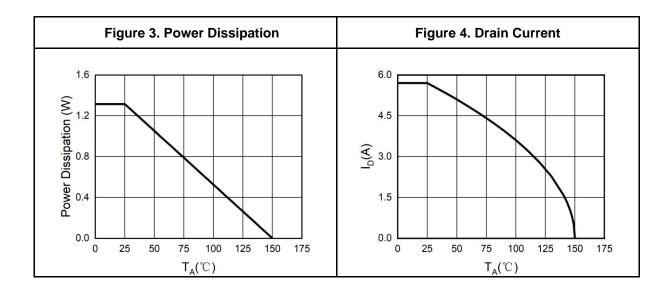
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

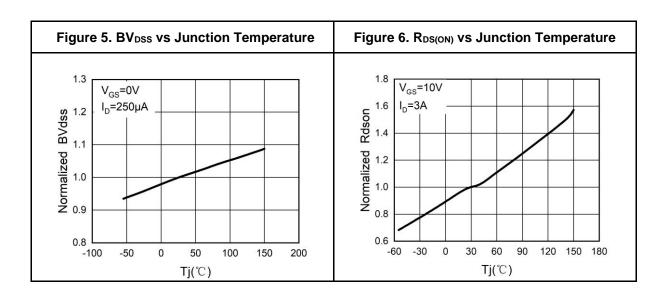
Notes 2.E_{AS} condition: $T_J=25^{\circ}C$, $V_{DD}=30V$, $V_G=10V$, $Rg=25\Omega$, L=0.5mH.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

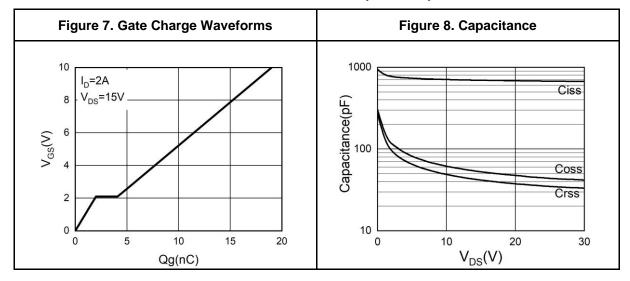
Typical Electrical And Thermal Characteristics (Curves)

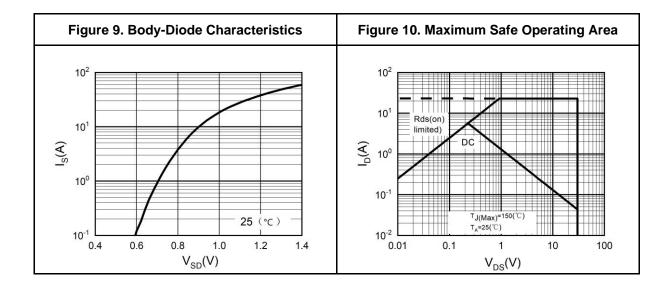




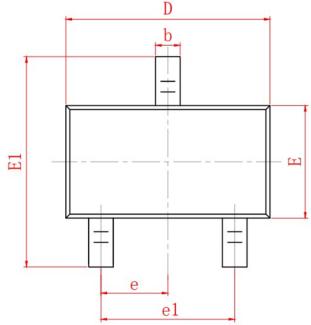


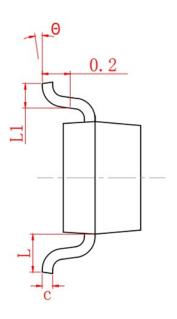
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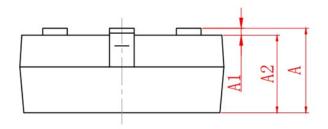




SOT-23 Package Information







SYMBOL	MIN	NOM	MAX	
А	0.90	1.05	1.20	
A1	0.00	0.05	0.10	
A2	0.90	1.00	1.10	
b	0.30	0.40	0.50	
С	0.08	0.10	0.15	
D	2.80	2.90	3.00	
Е	1.20	1.30	1.40	
E1	2.30	2.40	2.50	
L	0.30	0.40	0.50	
θ	0°	5°	10°	
L1	0.55 REF			
е	0.95 BSC			
e1	1.90 REF			

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Attention

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor.

The performances and characteristics of this product in the independent testing state are displayed in this document. Wuxi Shangjia Semiconductor can't guarantee of the performances and characteristics of this described product that mounted in the customer's products or equipments as same as that in the independent testing state. So the customer should evaluate and test devices mounted in the customer's products or equipments.

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